

△2 CONTACT: 1.27μm MIN GOLD IN PAD CONTACT AREA
1.27μm MIN TIN-LEAD ON PCB TAIL
OVER 1.27μm MIN NICKEL OVER ALL.
POST 1.27μm MIN NICKEL PLATED.

3 PLATED THROUGH HOLE REQUIREMENTS
PER 114-13056, FIGURE 4.

4 SEE TABLE FOR INTERCONNECTIONS TO
BACKPLANE CONNECTOR.

TABLE I
INTERCONNECTIONS WITH BACKPLANE CONNECTOR 1410140

TYPICAL INTERCONNECTIONS FOR EACH ODD-NUMBERED COLUMN (WAFER): 1		
CONTACT USAGE	DAUGHTERCARD CONNECTOR PIN	BACKPLANE CONNECTOR PIN
SIGNAL PAIR	a x	a x
	b x	b x
SIGNAL PAIR	d x	e x
	e x	f x
SIGNAL	g x	i x
GROUND(S)	c x, f x (ALL COMMONED)	c x, d x, g x, h x

TYPICAL INTERCONNECTIONS FOR EACH COLUMN (WAFER): 3-16		
CONTACT USAGE	DAUGHTERCARD CONNECTOR PIN	BACKPLANE CONNECTOR PIN
SIGNAL	ax	bx
SIGNAL	bx	cx
SIGNAL	dx	ex
SIGNAL	fx	gx
SIGNAL	gx	hx
GROUND	cx, ex, (ALL COMMONED)	ax, dx, fx, ix

NOTE: " x " DESIGNATES THE COLUMN NUMBER

